



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Title: **PROCESS FOR FORMING A DIRECT BUILD-UP LAYER ON AN
ENCAPSULATED DIE PACKAGES UTILIZING INTERMEDIATE STRUCTURES**

Docket No.: 884.791US1

Serial No.: 09/661,899

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Customer No.: 21186

Confirmation No.:

Commissioner for Patents

Notice of Allowance Date:

Attn: MAIL STOP ISSUE FEE

January 7, 2005

P.O. Box 1450

Alexandria, VA 22313-1450

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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, Attn – MAIL STOP ISSUE FEE, P.O. Box 1450, Alexandria, VA 22313-1450, on this 7 day of April, 2005.

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